DISCRETE SEMICONDUCTORS

DATA SHEET

BYV34 seriesDual rectifier diodes ultrafast

Product specification

October 1998



NXP Semiconductors Product specification

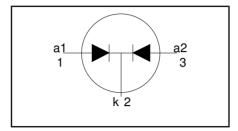
Dual rectifier diodes ultrafast

BYV34 series

FEATURES

- · Low forward volt drop
- · Fast switching
- · Soft recovery characteristic
- · High thermal cycling performance
- · Low thermal resistance

SYMBOL



QUICK REFERENCE DATA

$$V_R = 300 \text{ V} / 400 \text{ V} / 500 \text{ V}$$
 $V_F \le 1.05 \text{ V}$ $I_{O(AV)} = 20 \text{ A}$ $t_{rr} \le 60 \text{ ns}$

GENERAL DESCRIPTION

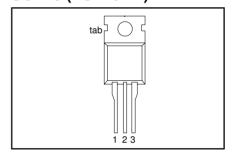
Dual, common cathode, ultra-fast, epitaxial rectifier diodes intended for use as output rectifiers in high frequency switched mode power supplies.

The BYV34 series is supplied in the conventional leaded SOT78 (TO220AB) package.

PINNING

PIN	DESCRIPTION		
1	anode 1		
2	cathode		
3	anode 2		
tab	cathode		

SOT78 (TO220AB)



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER CONDITIONS		MIN.	MAX.			UNIT
V _{RRM} V _{RWM} V _R	Peak repetitive reverse voltage Crest working reverse voltage Continuous reverse voltage	$\textbf{BYV34}$ $T_{mb} \leq 138^{\circ} \textbf{C}$	1 1 1	- 300 300 300 300	-400 400 400 400	-500 500 500 500	>
I _{O(AV)}	Average rectified output current (both diodes conducting) ¹	square wave; $\delta = 0.5$; $T_{mb} \le 115 ^{\circ}\text{C}$	-		20		Α
I _{FRM}	Repetitive peak forward current per diode	$t = 25 \mu s; δ = 0.5;$ $T_{mb} \le 115 °C$	-		20		Α
I _{FSM}	Non-repetitive peak forward	t = 10 ms	-		120		Α
	current per diode.	t = 8.3 ms sinusoidal; with reapplied	-		132		A
_	Storage temperature	V _{RRM(max)}	-40		150		°c
T _i stg	Storage temperature Operating junction temperature		-4 0 -		150		Ç

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th j-hs}$ $R_{th j-a}$	heatsink	per diode both diodes conducting in free air.		- - 60	2.4 1.6 -	K/W K/W K/W

¹ Neglecting switching and reverse current losses

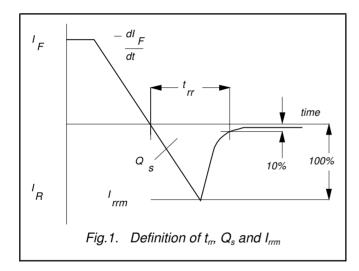
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ELECTRICAL CHARACTERISTICS

characteristics are per diode at T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{F}	Forward voltage	$I_F = 10 \text{ A}; T_j = 150^{\circ}\text{C}$	-	0.87	1.05	V
1.	<u>.</u>	$I_{\rm F} = 20 \text{A}$	-	1.10	1.35	V
I _R	Reverse current	$\dot{V}_{R} = V_{RRM}$	-	10	50	μA
		$V_{R} = V_{RRM}$; $T_{i} = 100 ^{\circ}C$	-	0.2	0.6	mA
Q_s	Reverse recovery charge	$V_{R} = V_{RRM}$; $T_{j} = 100 ^{\circ}\text{C}$ $I_{F} = 2 ^{\circ}\text{A to } V_{R} \geq 30 ^{\circ}\text{V}$;	-	50	60	nC
		$dI_F/dt = 20 A/\mu s$				
t _{rr}	Reverse recovery time	$I_F = 1 \text{ A to } V_B \ge 30 \text{ V};$	-	50	60	ns
		$dI_{F}/dt = 100 A/\mu s$				
I _{rrm}	Peak reverse recovery current	$I_{\rm F} = 10 \text{ A to } V_{\rm B} \ge 30 \text{ V};$	-	4.0	5.0	Α
''''	'	$dI_{F}/dt = 50 \text{ A/µs}; T_{i} = 100^{\circ}\text{C}$				
V_{fr}	Forward recovery voltage	$I_F = 10 \text{ A}; dI_F/dt = 10 \text{ A}/\mu\text{s}$	-	2.5	-	V



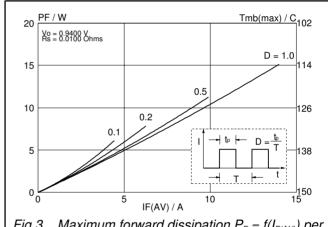
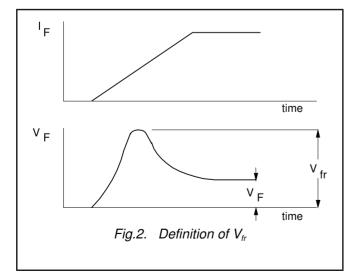


Fig.3. Maximum forward dissipation $P_F = f(I_{F(AV)})$ per diode; square wave where $I_{F(AV)} = I_{F(RMS)} x \sqrt{D}$.



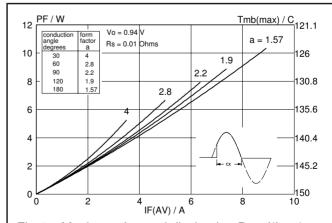
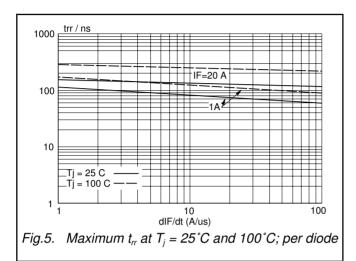


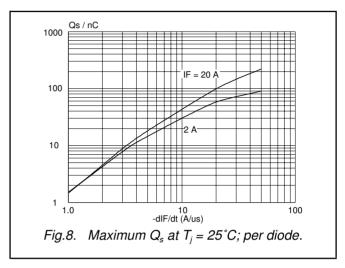
Fig.4. Maximum forward dissipation $P_F = f(I_{F(AV)})$ per diode; sinusoidal current waveform where a = form factor $= I_{F(RMS)} / I_{F(AV)}$.

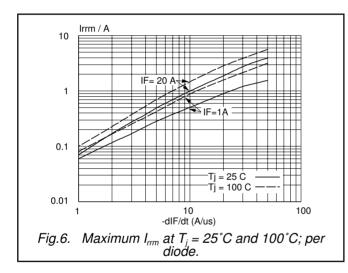
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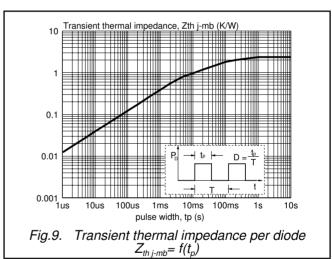
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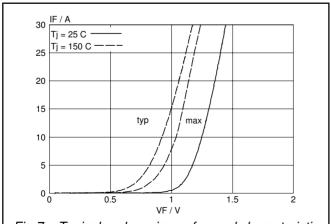


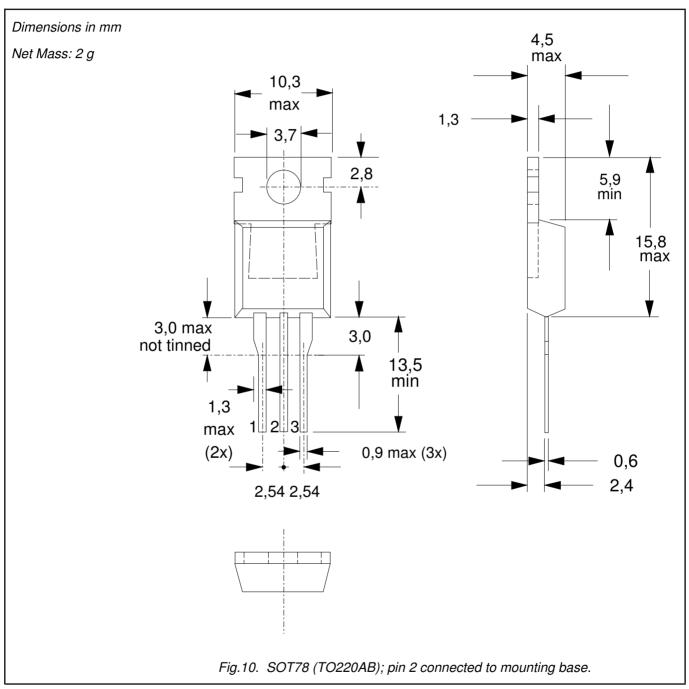
Fig.7. Typical and maximum forward characteristic

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MECHANICAL DATA



- Notes
 1. Refer to mounting instructions for SOT78 (TO220) envelopes.
 2. Epoxy meets UL94 V0 at 1/8".

Legal information

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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For additional information please visit: http://www.nxp.com
For sales offices addresses send e-mail to: salesaddresses@nxp.com

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